

SPECIFICATION

TO ALL WHOM IT MAY CONCERN:

BE IT KNOWN THAT WE, SEIJI SARAYAMA, a citizen of Japan residing at Miyagi, Japan, MASAHIKO SHIMADA, a citizen of Japan residing at Miyagi, Japan, HISANORI YAMANE, a citizen of Japan residing at Miyagi, Japan and HIROKAZU IWATA, a citizen of Japan residing at Miyagi, Japan have invented certain new and useful improvements in

PRODUCTION OF A GaN BULK CRYSTAL SUBSTRATE  
AND A SEMICONDUCTOR DEVICE FORMED ON  
A GaN BULK CRYSTAL SUBSTRATE

of which the following is a specification:-

BACKGROUND OF THE INVENTION

The present invention generally relates to semiconductor devices and more particularly to a semiconductor device having a GaN bulk crystal substrate.

GaN is a III-V compound semiconductor material having a large bandgap of blue to ultraviolet wavelength energy. Thus, intensive investigations are being made with regard to development of optical semiconductor devices having a GaN active layer for use particularly in optical information storage devices including a digital video data recorder (DVD). By using such a light emitting semiconductor device producing blue to ultraviolet wavelength optical radiation for the optical source, it is possible to increase the recording density of optical information storage devices.

Conventionally, a laser diode or light-emitting diode having a GaN active layer has been constructed on a sapphire substrate in view of the absence of technology of forming a GaN bulk crystal substrate.

FIG.1 shows the construction of a conventional GaN laser diode according to Nakamura, S., et al., Jpn. J. Appl. Phys. vol.36 (1997)

pp.L1568-L1571, Part 2, No.12A, 1 December 1997,  
constructed on a sapphire substrate 1.

Referring to FIG.1, the sapphire substrate 1 has a (0001) principal surface covered by a low-  
5 temperature GaN buffer layer 2, and includes a GaN buffer layer 3 of n-type grown further on the buffer layer 2. The GaN buffer layer 3 includes a lower layer part 3a and an upper layer part 3b both of n-type, with an intervening SiO<sub>2</sub> mask pattern 4  
10 provided such that the SiO<sub>2</sub> mask pattern 4 is embedded between the lower layer part 3a and the upper layer part 3b. More specifically, the SiO<sub>2</sub> mask pattern 4 is formed on the lower GaN buffer layer part 3a, followed by a patterning process thereof to  
15 form an opening 4A in the SiO<sub>2</sub> mask pattern 4.

After the formation of the SiO<sub>2</sub> mask pattern 4, the upper GaN layer part 3b is formed by an epitaxial lateral overgrowth (ELO) process in which the layer 3b is grown laterally on the SiO<sub>2</sub>  
20 mask 4. Thereby, desired epitaxy is achieved with regard to the lower GaN layer part 3a at the opening 4A in the SiO<sub>2</sub> mask pattern 4. By growing the GaN layer part 3b as such, it is possible to prevent the defects, which are formed in the GaN layer part 3a  
25 due to the large lattice misfit between GaN and

sapphire, from penetrating into the upper GaN layer part 3b.

On the upper GaN layer 3b, a strained super-lattice structure 5 having an n-type  $\text{Al}_{0.14}\text{Ga}_{0.86}\text{N}/\text{GaN}$  modulation doped structure is formed, with an intervening InGaN layer 5A of the n-type having a composition  $\text{In}_{0.1}\text{Ga}_{0.9}\text{N}$  interposed between the upper GaN layer part 3b and the strained superlattice structure 5. By providing the strained superlattice structure 5 as such, dislocations that are originated at the surface of the sapphire substrate 1 and extending in the upward direction are intercepted and trapped.

On the strained superlattice structure 5, a lower cladding layer 6 of n-type GaN is formed, and an active layer 7 having an MQW structure of  $\text{In}_{0.01}\text{Ga}_{0.98}\text{N}/\text{In}_{0.15}\text{Ga}_{0.85}\text{N}$  is formed on the cladding layer 6. Further, an upper cladding layer 8 of p-type GaN is formed on the active layer 7, with an intervening electron blocking layer 7A of p-type  $\text{AlGaN}$  having a composition of  $\text{Al}_{0.2}\text{Ga}_{0.8}\text{N}$  interposed between the active layer 7 and the upper cladding layer 8.

On the upper cladding layer 8, another strained superlattice structure 9 of a p-type

$\text{Al}_{0.14}\text{Ga}_{0.86}\text{N}/\text{GaN}$  modulation doped structure is formed such that the superlattice structure 9 is covered by a p-type GaN cap layer 10. Further, a p-type electrode 11 is formed in contact with the cap layer 10 and an n-type electrode 12 is formed in contact with the n-type GaN buffer layer 3b.

It is reported that the laser diode of FIG.1 oscillates successfully with a practical lifetime, indicating that the defect density in the active layer 7 is reduced successfully.

On the other hand, the laser diode of FIG.1 cannot eliminate the defects completely, and there remain substantial defects particularly in correspondence to the part on the  $\text{SiO}_2$  mask 4 as represented in FIG.2. See Nakamura S. et al., op cit. It should be noted that such defects formed on the  $\text{SiO}_2$  mask 4 easily penetrate through the strained superlattice structure 5 and the lower cladding layer 6 and reach the active layer 7.

In view of the foregoing concentration of the defects in the central part of the  $\text{SiO}_2$  mask pattern 4, the laser diode of FIG.1 uses the part of the semiconductor epitaxial structure located on the opening 4A of the  $\text{SiO}_2$  mask 4, by forming a mesa structure M in correspondence to the opening 4A.

However, the defect-free region formed on the opening 4A has a lateral size of only several microns, and thus, it is difficult to construct a high-power laser diode based on the construction of FIG.1. When the 5 laser diode of FIG.1 is driven at a high power, the area of optical emission in the active region extends inevitably across the defects, and the laser diode is damaged as a result of optical absorption caused by the defects. Further, the laser diode of FIG.1 having 10 such a construction has other various drawbacks associated with the defects in the semiconductor epitaxial layers, such as large threshold current, limited lifetime, and the like. Further, the laser diode of FIG.1 has a drawback, in view of the fact 15 that the sapphire substrate is an insulating substrate, in that it is not possible to provide an electrode on the substrate. As represented in FIG.1, it is necessary to expose the top surface of the n-type GaN buffer layer 3 by an etching process in 20 order to provide the n-type electrode 12, while such an etching process complicates the fabrication process of the laser diode. In addition, the increased distance between the active layer 7 and the n-type electrode 12 causes the problem of increased 25 resistance of the current path, while such an

increased resistance of the current path deteriorates the high-speed response of the laser diode.

Further, the conventional laser diode of FIG.1 suffers from the problem of poor quality of 5 mirror surfaces defining the optical cavity. Due to the fact that the sapphire single crystal constituting the substrate 1 belongs to hexagonal crystal system, formation of the optical cavity cannot be achieved by a simple cleaving process. It 10 has been therefore necessary to form the mirror surfaces, when fabricating the laser diode of FIG.1 by conducting a dry etching process, while the mirror surface thus formed by a dry etching process has a poor quality.

15 Because of the foregoing reasons, as well as because of other various reasons not mentioned here, it is desired to form the substrate of the GaN laser diode by a bulk crystal GaN and form the laser diode directly on the GaN bulk crystal substrate.

20 With regard to the art of growing a bulk crystal GaN, there is a successful attempt reported by Porowski (Porowski, S., J. Crystal Growth 189/190 (1998) pp.153-158, in which a GaN bulk crystal is synthesized from a Ga melt under an elevated 25 temperature of 1400 - 1700°C and an elevated N<sub>2</sub>

pressure of 12 - 20 kbar (1.2 - 2 GPa). This process, however, can only provide an extremely small crystal in the order of 1 cm in diameter at best. Further the process of Porowski requires a specially built pressure-resistant apparatus and a long time is needed for loading or unloading a source material, or increasing or decreasing the pressure and temperature. Thus, the process of this prior art would not be a realistic solution for mass-production of a GaN bulk crystal substrate. It should be noted that the reaction vessel of Porowski has to withstand the foregoing extremely high pressure, which is rarely encountered in industrial process, under the temperature exceeding 1400° C.

Further, there is a known process of growing a GaN bulk crystal without using an extremely high pressure environment for growing a GaN bulk crystal as reported by Yamane, H., et al., *Chem. Mater.* 1997, 9, 413 - 416. More specifically, the process of Yamane et al. successfully avoids the use of the extremely high-pressure used in Porowski, by conducting the growth of the GaN bulk crystal from a Ga melt in the presence of a Na flux.

According to the process of Yamane, a metallic Ga source and a  $\text{NaN}_3$  (sodium azide) flux are

confined in a pressure-resistance reaction vessel of stainless steel together with a N<sub>2</sub> atmosphere, and the reaction vessel is heated to a temperature of 600 - 800°C and held for a duration of 24 - 100 hours. As 5 a result of the heating, the pressure inside the reaction vessel is elevated to the order of 100 kg/cm<sup>2</sup> (about 10 MPa), which is substantially lower than the pressure used by Porowski. As a result of the reaction, GaN crystals are precipitated from the 10 melt of a Na-Ga system. In view of the relatively low pressure and low temperature needed for the reaction, the process of Yamane et al. is much easier to implement.

On the other hand, the process of Yamane 15 relies upon the initially confined N<sub>2</sub> molecules in the atmosphere and the N atoms contained in the NaN<sub>3</sub> flux for the source of N. Thus, when the reaction proceeds, the N<sub>2</sub> molecules in the atmosphere or the N atoms in the Na-Ga melt are depleted with the 20 precipitation of the GaN crystal, and there appears a limitation in growing a large bulk crystal of GaN. The GaN crystals obtained by the process of Yamane et al. typically have a size of 1mm or less in diameter. Thus, the process of Yamane et al. op cit., while 25 being successful in forming a GaN bulk crystal at a

relatively low pressure and temperature, cannot be used for a mass production of a GaN substrate in the industrial base.

5        SUMMARY OF THE INVENTION

Accordingly, it is a general object of the present invention to provide a novel and useful GaN semiconductor device having a bulk crystal substrate wherein the foregoing problems are eliminated.

10        Another and more specific object of the present invention is to provide a process of making a bulk crystal substrate of a GaN single crystal.

Another object of the present invention is to provide a process of fabricating a GaN 15 semiconductor device having a bulk crystal substrate of a GaN single crystal.

Another object of the present invention is to provide a bulk crystal substrate of a single crystal GaN.

20        Another object of the present invention is to provide an optical semiconductor device having a bulk crystal substrate of a GaN single crystal.

Another object of the present invention is to provide an electron device having a bulk crystal 25 substrate of a GaN single crystal.

Another object of the present invention is to provide an apparatus for making a bulk crystal substrate of a GaN single crystal.

According to the present invention, a high-quality GaN bulk crystal substrate is obtained with a process suitable for mass-production, by continuously supplying N so as to compensate for the depletion of N occurring in the system in which precipitation of a GaN single crystal takes place. By using the GaN bulk crystal substrate thus obtained, it is possible to fabricate an optical semiconductor device that produces an optical radiation of blue to ultraviolet wavelength with a large optical power. Further, the GaN bulk crystal substrate can be used as a substrate of an electron device such as HEMT.

Other objects and further features of the present invention will become apparent from the following detailed description when read in conjunction with the attached drawings.

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BRIEF DESCRIPTION OF THE DRAWINGS

FIG.1 is a diagram showing the construction of a conventional laser diode constructed on a sapphire substrate;

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FIG.2 is a diagram showing the problem

associated with the laser diode of FIG.1;

FIG.3 is a diagram showing the construction of a growth apparatus used in a first embodiment of the present invention for growing a GaN bulk crystal;

5 FIGS.4A and 4B are diagrams showing a part of the apparatus of FIG.3 in detail;

FIG.5 is a diagram showing a cathode luminescent spectrum of a GaN bulk crystal obtained in the first embodiment;

10 FIG.6 is a diagram showing a control of GaN composition in the growth apparatus of FIG.3;

FIG.7 is a diagram showing the construction of a growth apparatus used in a second embodiment of the present invention for growing a GaN bulk crystal;

15 FIG.8 is a diagram showing the construction of a growth apparatus used in a third embodiment of the present invention for growing a GaN bulk crystal;

FIG.9 is a diagram showing the construction of a growth apparatus used in a fourth embodiment of 20 the present invention for growing a GaN bulk crystal;

FIG.10 is a diagram showing the construction of a growth apparatus used in a fifth embodiment of the present invention for growing a GaN bulk crystal;

25 FIG.11 is a diagram showing the

construction of a growth apparatus used in a sixth embodiment of the present invention for growing a GaN bulk crystal;

5 FIG.12 is a diagram showing the construction of a growth apparatus used in a seventh embodiment of the present invention for growing a GaN bulk crystal;

10 FIG.13 is a diagram showing the construction of a seed crystal used in the growth apparatus of FIG.12;

FIG.14 is a diagram showing the construction of a growth apparatus used in an eighth embodiment of the present invention for growing a GaN bulk crystal;

15 FIG.15A and 15B are diagrams showing a part of the growth apparatus of FIG.14;

FIG.16 is a diagram showing the growth apparatus of FIG.14 in the state in which a growth of the GaN bulk crystal has been made;

20 FIG.17 is a diagram showing the construction of a growth apparatus used in a ninth embodiment of the present invention for growing a GaN bulk crystal;

25 FIG.18 is a diagram showing the construction of a growth apparatus used in a tenth

embodiment of the present invention for growing a GaN bulk crystal;

FIG.19 is a diagram showing X-ray diffraction data obtained for a GaN bulk crystal  
5 according to an eleventh embodiment of the present invention;

FIG.20 is a diagram showing the construction of a laser diode having a GaN bulk crystal substrate according to a twelfth embodiment  
10 of the present invention; and

FIG.21 is a diagram showing the construction of a HEMT having a GaN bulk crystal substrate according to a thirteenth embodiment of the present invention.

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#### DETAILED DESCRIPTION OF THE INVENTION

##### [FIRST EMBODIMENT]

FIG.3 shows the construction of a growth apparatus 100 used in a first embodiment of the  
20 present invention for growing a GaN bulk crystal.

Referring to FIG.3, the growth apparatus 100 includes a pressure-resistant reaction vessel 101 typically of a stainless steel having an inner diameter of about 75 mm and a length of about 300 mm  
25 and accommodates therein a crucible 102 of Nb or BN.

As will be explained later, the crucible 102 is loaded with a starting material of metallic Ga and a NaN<sub>3</sub> flux and is confined in the reaction vessel 101 together with an N<sub>2</sub> atmosphere 107. Further, the 5 reaction vessel 101 is supplied with N<sub>2</sub> or a gaseous compound of N from an external source via a regulator valve 109 and an inlet 108. The reaction vessel 101 thus loaded with the starting material in the crucible 102 is heated by energizing heaters 110 and 10 111 to a temperature of 650 - 850°C, and the pressure inside the reaction vessel is regulated to a moderate value of about 5MPa by controlling the valve 109. By holding the temperature and the pressure, a precipitation of GaN bulk crystal takes place from a 15 Na-Ga melt, which is formed in the crucible 102 as a result of the melting of the starting material.

FIG.4A shows the loading of the starting material in the crucible 102, while FIG.4B shows the state in which the source material has caused a 20 melting.

Referring to FIG.4A, a high-purity metallic Ga and a high-purity metallic Na are weighed carefully and loaded into the crucible 102, wherein the foregoing process of weighing and loading are 25 conducted in the N<sub>2</sub> atmosphere. It is also possible

to use high-purity  $\text{NaN}_3$  in place of high-purity metallic Na source.

In the state of FIG.4B, on the other hand, there appears a melt 102A of the Na-Ga system in the 5 crucible 102 and crystallization of GaN takes place from various parts of the melt 102A including a free surface of the melt and a sidewall or bottom wall of the crucible 102. There, it was observed that a large single crystal 102B of GaN grows on the melt free 10 surface contacting with the atmosphere and fine needle-like GaN crystals 102C grow on the sidewall or bottom wall of the crucible 102.

With the growth of the GaN crystals, particularly with the growth of the GaN single 15 crystal 102B, N in the atmosphere is consumed and the pressure inside the reaction vessel gradually falls as a result of depletion of N in the atmosphere. Thus, in the present embodiment, the depletion of N in the atmosphere 107 is compensated for by replenishing  $\text{N}_2$  20 or a compound of N such as  $\text{NH}_3$  from an external source. Thereby, the growth of the GaN single crystal 102B continues at the melt free surface and a large GaN single crystal suitable for use in an optical semiconductor device such as a laser diode or light- 25 emitting diode as a GaN bulk crystal substrate is

obtained. The construction of FIG.3 can easily produce the GaN single crystal 102B with a thickness of  $100\mu\text{m}$  or more. The GaN single crystal 102B thus formed at the temperature of  $650 - 850^\circ\text{C}$  has a 5 hexagonal crystal symmetry.

FIG.5 shows the cathode luminescent spectrum of the GaN single crystal 102B thus obtained in comparison with the cathode luminescent spectrum of a GaN thick film grown on a sapphire substrate or 10 an SiC substrate.

Referring to FIG.5, it can be seen that the GaN crystal 102B of the present embodiment shows a distinct and strong peak corresponding to the band edge of GaN at the wavelength of about 360 nm. 15 Further, it can be seen that no other peak exists in the GaN single crystal 102B of the present embodiment. The result of FIG.5 indicates that the GaN crystal 102B thus formed has a defect density of less than  $10^2 - 10^3\text{cm}^{-3}$ . Thus, the GaN single crystal 102B is 20 suitable for use as a bulk GaN substrate of various optical semiconductor devices including a laser diode and a light-emitting diode as noted already. Hereinafter, the GaN single crystal 102B will be called a GaN bulk crystal in view of application to a 25 GaN bulk crystal substrate.

Contrary to the present embodiment, the GaN thick film formed on the sapphire substrate or formed on the SiC substrate shows a remarkable peak at the wavelength of about 600 nm corresponding to deep 5 impurity levels. This clearly indicates that the GaN thick film thus formed on a sapphire substrate or an SiC substrate contains a substantial amount of defects. Associated with the high level of defects, it can be seen that the peak strength for the band 10 edge is substantially smaller than the case of the GaN bulk crystal 102B of the present embodiment.

In the growth process of FIG.4B, it should be noted that there appears also an intermetallic compound 102D of GaNa along the sidewall and bottom 15 surface of the crucible 102 indicated in FIG.4B by a broken line. Thus, the region represented in FIG.4B by the broken line in fact includes the fine GaN crystals 102C and the GaNa intermetallic compound 102D in the form of a mixture. The GaN fine crystals 20 102C or the GaNa intermetallic compound 102D thus formed releases Ga into the melt 102A, and the Ga atoms thus released contribute to the growth of the GaN bulk crystal 102B when transported to the melt surface.

25 Thus, by continuously replenishing N<sub>2</sub> or

NH<sub>3</sub>, the growth process of the GaN bulk crystal 102B continues until Ga in the melt 102A is used up.

FIG.6 shows the control of the N<sub>2</sub> pressure in the atmosphere 107 with the growth of the GaN bulk 5 crystal 102B from the melt 102A.

Referring to FIG.6, it can be seen that the N<sub>2</sub> pressure a necessary for maintaining the stoichiometric composition for the GaN bulk crystal 102B changes depending on the Ga content in the melt 10 102A represented in the horizontal axis. When the N<sub>2</sub> pressure in the atmosphere 107 is fixed ( $a_1 = a_2$ ), it is not possible to maintain the stoichiometric composition for the GaN bulk crystal 102B. Thus, the present invention changes the N<sub>2</sub> pressure a in the 15 atmosphere 107 with the progress of growth of the GaN bulk crystal 102B as represented as  $a_1 \neq a_2$ .

[SECOND EMBODIMENT]

FIG.7 shows the construction of a growth 20 apparatus 200 according to a second embodiment of the present invention, wherein those parts corresponding to the parts described previously are designated by the same reference numerals and the description there of will be omitted.

25 Referring to FIG.7, the present embodiment

uses heaters 111A and 111B in place of the heater 111 and induces a temperature gradient in the melt 102A for facilitating transport of Ga from the GaN fine crystals 102C or the GaNa intermetallic compound 102D 5 to the melt surface.

More specifically, the heater 111B is provided in correspondence to the bottom part of the crucible 102 and controls, together with the heart 111A, the melt temperature at the bottom part of the 10 crucible 102 lower than the melt surface. As a result of energization of the heaters 111A and 111B, a temperature gradient shown in FIG.7 is induced.

Due to the increased temperature at the bottom part of the crucible 102, undesirable 15 precipitation of GaN crystals on bottom surface of the crucible 102 is minimized, and the growth of the GaN bulk crystal 102B on the melt surface is promoted substantially. When a GaN fine crystal 102C is formed, such a GaN fine crystal 102C is immediately dissolved 20 into the melt 102A and no substantial deposition occurs on the bottom part of the crucible 102. Further, the intermetallic compound of GaNa, formed at a temperature lower than about 530°C, acts also as the source of Ga and Na in the melt 102A.

25 Similarly to the first embodiment, the GaN

bulk crystal 102B formed according to the present embodiment has a defect density in the order of  $10^2$  -  $10^3 \text{ cm}^{-3}$  or less. Thus, the GaN bulk crystal 102B is suitable for a bulk GaN substrate of various optical 5 semiconductor devices including a laser diode and a light-emitting diode.

[THIRD EMBODIMENT]

FIG.8 shows the construction of a growth 10 apparatus 300 according to a third embodiment of the present invention, wherein those parts corresponding to the parts described previously are designated by the same reference numerals and the description thereof will be omitted.

15 Referring to FIG.8, the present embodiment is a modification of the embodiment of FIG.7 and uses the heaters 110 and 111, described with reference to the growth apparatus 100 for inducing the desired temperature gradient. As other aspects of the present 20 embodiment are substantially the same as those of the previous embodiment, further description will be omitted.

[FOURTH EMBODIMENT]

25 FIG.9 shows the construction of a growth

apparatus 400 according to a fourth embodiment of the present invention, wherein those parts corresponding to the parts described previously are designated by the same reference numerals and the description thereof will be omitted.

Referring to FIG.9, the growth apparatus 400 has a construction similar to that of FIG.3, except that there is provided a container 103 holding a metallic Ga source 104 inside the reaction vessel 101. The container 103 is provided at a first end of a tube 103A extending outside of the reaction vessel 101, and there is provided a pressure regulator 106 at a second, opposite end of the tube 103. The pressure regulator 106 is supplied with a pressurized  $N_2$  gas from an external source and causes a molten Ga, formed in the container 103 as a result of heating, to drip to the Na-Ga melt 102A in the crucible 102 via a hole 105 formed at a bottom part of the container 103.

According to the construction of FIG.9, depletion of Ga in the melt 102A is replenished from the Ga source 104 and a thickness of 300  $\mu m$  or more is obtained for the GaN bulk crystal 102B as a result of the continuous crystal growth.

Similarly to the previous embodiments, the

GaN bulk crystal 102B formed according to the present embodiment has a defect density of  $10^2$  -  $10^3\text{cm}^{-3}$  or less. Thus, the GaN bulk crystal 102B of the present embodiment is suitable for use as a bulk GaN substrate of various optical semiconductor devices including a laser diode and a light-emitting diode.

[FIFTH EMBODIMENT]

FIG.10 shows the construction of a growth apparatus 500 according to a fifth embodiment of the present invention, wherein those parts corresponding to the parts described previously are designated by the same reference numerals and the description thereof will be omitted.

Referring to FIG.10, the growth apparatus 500 has a construction similar to that of the growth apparatus of FIG.9, except that there is provided an outer pressure vessel 112 outside the reaction vessel 101, and the space between the reaction vessel 101 and the outer pressure vessel 112 is filled with a pressurized gas such as  $\text{N}_2$ , which is introduced via a regulator 114 and an inlet 113.

By providing the pressure vessel 112 outside the reaction vessel 101, the pressurized reaction vessel 101 is supported from outside and the

design of the reaction vessel 101 becomes substantially easier. As represented in FIG.10, there is provided a thermal insulator 115 between the heater 110 or 111 and the outer pressure vessel 112 and the temperature rise of the pressure vessel 112 is avoided. Thereby, the pressure vessel 112 maintains a large mechanical strength even when the inner, reaction vessel 101 is heated to the temperature exceeding 600 or 700° C. In order to avoid the decrease of mechanical strength, it is possible to provide a water cooling system (not shown) on the outer pressure vessel 112.

The outer pressure vessel 112 can be provided also to the growing apparatuses 100 - 300 explained before as well as to the growing apparatuses to be described hereinafter.

As other features of the present embodiment are substantially the same as those of the previous embodiments, further description thereof will be omitted.

[SIXTH EMBODIMENT]

FIG.11 shows the construction of a growing apparatus 600 according to a sixth embodiment of the present invention, wherein those parts corresponding

to the parts described previously are designated by the same reference numerals and the description thereof will be omitted.

Referring to FIG.11, the growing apparatus 600 has a construction similar to that of the growing apparatus 100 of FIG.3, except that there is provided a holder 601 holding a Ga-Na melt outside the reaction vessel 101 and the Ga-Na melt in the holder 601 is supplied into the reaction vessel 101 and to the melt 102A in the crucible 102 via a tube 601A penetrating through a wall of the reaction vessel 101, in response to a pressurization of the holder 601 by a pressurized gas such as an N<sub>2</sub> gas supplied via a line 602.

According to the present embodiment, the depletion of Ga in the melt 102A is replenished together with the Na flux, and the growth of the GaN bulk crystal 102B at the free surface of the melt 102A is conducted continuously. It should be noted that depletion of N in the system is also replenished by the external N source similarly to the previous embodiments. As a result, a high-quality GaN bulk crystal suitable for use as a substrate of various optical semiconductor devices is obtained with a thickness well exceeding 100 $\mu$ m, generally about 300 $\mu$

m or more.

[SEVENTH EMBODIMENT]

FIG.12 shows the construction of a growth apparatus 700 according to a seventh embodiment of the present invention, wherein those parts corresponding to the parts described previously are designated by the same reference numerals and the description thereof will be omitted.

Referring to FIG.12, the growing apparatus 700 has a construction similar to that of the growing apparatus 600 of the previous embodiment, except that there is provided a rod 702 carrying a seed crystal 701 at a tip end thereof in contact with the free surface of the melt 102A in the crucible 102. Further there is provided a motor 703 for pulling up the rod 702, and there occurs a continuous growth of the GaN bulk crystal 102B at the melt surface with the pulling up of the rod 702. Thereby, an ingot of a GaN bulk crystal is obtained.

By slicing the GaN bulk crystal ingot thus obtained, it is possible to mass produce the GaN bulk crystal substrate for use in various optical semiconductor devices including a laser diode and a light-emitting diode.

FIG.13 shows an example of the seed crystal 701 provided at the tip end of the rod 702.

Referring to FIG.13, the seed crystal 702 is formed to have a slab shape with a width w and a thickness d corresponding to the width and thickness of the GaN substrate to be formed. Thus, by pulling up the rod 702 straight in the upward direction, a slab-shaped GaN bulk crystal is grown continuously. Thus, by merely polishing the surface of the GaN bulk crystal slab, followed by a cleaving process, it is possible to mass-produce the GaN bulk crystal substrate having a quality suitable for use in various optical semiconductor devices including a laser diode and a light-emitting diode.

As other features of the present embodiment is more or less the same as those of the previous embodiments, further description thereof will be omitted.

20 [EIGHTH EMBODIMENT]

FIG.14 shows the construction of a growing apparatus 800 according to an eighth embodiment of the present invention, wherein those parts corresponding to the parts described previously are 25 designated by the same reference numerals and the

description thereof will be omitted.

Referring to FIG.14, the growing apparatus 800 has a construction similar to that of the growing apparatus 700 of the previous embodiment, except that 5 a cover member 803 is provided so as to cover the free surface of the melt 102A. Further, the container 601 of a Na-Ga melt is eliminated and a container 801 having a heating mechanism 801A and containing therein a molten Na is provided outside the reaction 10 vessel 101. Thereby, a vapor of Na is supplied from the container 801 into the interior of the reaction vessel 101 via a tube 802 and the Na vapor is added to the atmosphere 107 therein.

According to the present embodiment, 15 uncontrolled precipitation of the GaN fine crystals 102C on the sidewall or bottom surface of the crucible (see FIG.4B) is minimized, by controlling the vapor pressure of Na from the container 801. Further, no GaN precipitation occurs on the melt free 20 surface, as the free surface of the melt 102A is covered by the cover member 803, except for a central part of the melt where there is formed an opening 803A in the cover member 803 for allowing the seed crystal 701 on the rod 702 to make a contact with the 25 surface of the melt 102A.

Thus, according to the construction of FIG.14, the Na vapor flux acts selectively at the part of the melt 102A where the growth of the bulk GaN ingot is made, and the uncontrolled precipitation 5 of the GaN fine crystals 102C is effectively suppressed.

It should be noted that cover member 803 has a variable geometry construction formed of a number of small, fan-shaped members, in which the 10 opening 803A can be changed with the growth of the GaN bulk crystal 102B in the form of ingot by moving the fan-shaped members in a direction of an arrow Q as represented in FIGS.15A and 15B, wherein FIG.15A shows the state in which the central opening 803A of 15 the cover member 803 is closed while FIG.15B shows the state in which the opening 803A has been expanded for allowing the growth of the GaN bulk crystal ingot 102B as represented in FIG.16. It should be noted that FIG.16 shows the growing apparatus 800 in the 20 state that there occurred a growth of the GaN bulk crystal 102B in the form of ingot.

[NINTH EMBODIMENT]

FIG.17 shows the construction of a growing 25 apparatus 900 according to a tenth embodiment of the

present invention, wherein those parts corresponding to the parts described previously are designated by the same reference numeral and the description thereof will be omitted.

5 Referring to FIG.17, the growing apparatus 900 has a construction similar to that of the growing apparatus 800 of the previous embodiment, except that the tube 802 supplying the Na vapor flux has a sleeve part 802A surrounding the rod 702. The sleeve part 10 802A extends along the rod 702 and has an opening 802C in correspondence to the surface of the melt 102A where the opening 803A is formed in the cover member 803 for the growth of the GaN bulk crystal 102B.

15 According to the construction of FIG.17, the Na flux is supplied selectively to the part where the growth of the GaN bulk crystal 102B takes place and an efficient growth becomes possible.

20 As other aspects of the present embodiment are the same as those of the previous embodiment, further description thereof will be omitted.

[TENTH EMBODIMENT]

FIG.18 shows the construction of a growing 25 apparatus 1000 according to a ninth embodiment of the

present invention wherein those parts corresponding to the parts described previously are designated by the same reference numerals and the description thereof will be omitted.

5 Referring to FIG.18, the growing apparatus 1000 has a construction similar to that of the growing apparatus 700 of FIG.12, except that the rod 702 driven by the motor 703 and pulling up the seed 701 in the upward direction is replaced by a rod 702' 10 driven by a motor 703' and pulls down a seed 701' in the downward direction. Thus, as represented in FIG.18, the GaN bulk crystal 102B forms an ingot grown inside the melt 102A. As other aspects of the present invention is the same as those described 15 before, further description of the present embodiment will be omitted.

[ELEVENTH EMBODIMENT]

In any of the foregoing first through tenth 20 embodiments, the growth of the GaN bulk crystal 102B has been achieved at the temperature of 650 - 850°C under the presence of a Na flux. As mentioned before, the GaN bulk crystal 102B thus obtained has a symmetry of hexagonal crystal system.

25 On the other hand, the inventor of the

present invention has discovered that a cubic GaN crystal is obtained as the bulk GaN crystal 102B provided that the growth is made at a temperature of less than 600°C under the presence of Na, or when the 5 growth is made at a temperature of 650 - 850°C under the presence of K. K may be introduced into the system in the form of a high-purity metallic K starting material, similarly to the case represented in FIG.4A.

10 FIG.19 shows X-ray diffraction data obtained for a GaN bulk crystal grown by the apparatus of FIG.3 as the bulk crystal 102B at a temperature of 750°C under the total pressure of 7MPa in the reaction vessel 101. In FIG.19, it should be noted that the  $F_o$  represents 15 the structural factor obtained from the diffraction pattern for each of the reflections  $(h k l)$ , while  $F_c$  represents the structural factor calculated from a cubic zinc blende structure. From the diffraction pattern, it was confirmed that the cubic GaN bulk 20 crystal 102B thus formed has a lattice constant  $a_0$  of  $4.5062 \pm 0.0009\text{\AA}$ . Thus, in the calculation of the foregoing structural factor  $F_c$ , the lattice constant 25  $a_0$  of  $4.5062 \pm 0.0009\text{\AA}$  is assumed as the basis of the calculation. Further, FIG.19 shows an error factor s defined as

$$s = \sum |F_o - F_c| / \sum F_b.$$

Referring to FIG.19, it can be seen that there is an excellent agreement between the observed structural factor and the calculated structural 5 factor assuming the cubic zinc blende structure for the obtained GaN bulk crystal 102B. It can be safely concluded that the GaN bulk crystal 102B obtained in the present embodiment is a 100% cubic GaN crystal. From the X-ray diffraction analysis, existence of 10 hexagonal GaN crystal was not detected. Further it was confirmed that the cubic GaN bulk crystal 102B thus formed provides a cathode luminescent peak substantially identical with the spectrum of FIG.5. In other words, the cubic GaN bulk crystal of the 15 present embodiment contains little deep impurity levels or defects and has an excellent quality characterized by a defect density of  $10^2$  -  $10^3\text{cm}^{-3}$  or less.

In view of increasing defect density in the 20 GaN crystals grown at low temperatures, and further in view of the fact that a mixture of cubic GaN and hexagonal GaN appears when the growth of the GaN bulk crystal is conducted at the temperature of 600°C or lower under presence of Na flux, it is preferred to 25 grow a cubic GaN bulk crystal at the temperature of

650 - 850°C under presence of a K flux.

[TWELFTH EMBODIMENT]

FIG.20 shows the construction of a laser  
5 diode 150 of edge-emission type according to a  
twelfth embodiment of the present invention.

Referring to FIG.20, the laser diode 150 is  
constructed on a GaN bulk crystal substrate 151  
produced in any of the process explained before. More  
10 specifically, the GaN bulk crystal substrate 151 has  
a high crystal quality characterized by a defect  
density of  $10^2$  -  $10^3\text{cm}^{-3}$  or less.

On the GaN bulk crystal substrate 151,  
there is provided a lower cladding layer 152 of n-  
15 type AlGaN epitaxially with respect to the substrate  
151 and an optical waveguide layer 153 of n-type GaN  
is formed on the lower cladding layer 152 epitaxially.

On the optical waveguide layer 153, there  
is provided an active layer 154 of MQW structure  
20 including an alternate stacking of quantum well  
layers of undoped InGaN having a composition  
represented as  $\text{In}_x\text{Ga}_{1-x}\text{N}$  ( $x=0.15$ ) and barrier layers  
of undoped InGaN having a composition represented as  
 $\text{In}_y\text{Ga}_{1-y}\text{N}$  ( $y=0.02$ ). The active layer 154 is covered by  
25 an optical waveguide layer 155 of p-type GaN, and an

upper cladding layer 156 of p-type AlGaN is formed epitaxially on the optical waveguide layer 155.

Further, a contact layer 157 of p-type GaN is formed on the upper cladding layer 156.

5           The contact layer 157 and the underlying upper cladding layer 156 are subjected to a patterning process to form a loss-guide structure extending in the axial direction of the laser diode 150 and the loss-guide structure thus formed is  
10        covered by an SiO<sub>2</sub> film 158. The SiO<sub>2</sub> film 158 is formed with an opening 158A extending in the laser axial direction for exposing the contact layer 157, and a p-type electrode 159 is provided on the SiO<sub>2</sub> film 158 in contact with the contact layer 157 at the  
15        opening 158A.

Further, an n-type electrode 160 is provided at a bottom surface of the GaN bulk crystal substrate 151.

After forming the laser structure as such,  
20        the layered semiconductor body including the GaN substrate 151 and the epitaxial layers 151 - 157 is subjected to a cleaving process to form mirror surfaces M1 and M2 defining an optical cavity. Thereby, the laser diode produces a blue to  
25        ultraviolet optical beam as a result of stimulated

emission and optical amplification occurring in the optical cavity, as represented in FIG.20 by an arrow.

According to the present invention, the optical cavity is formed by a simple cleaving process and the quality of the mirror surfaces M1 and M2 defining the optical cavity is improved substantially. Thereby, threshold of laser oscillation is lowered substantially. Further, the laser diode 150 carries the n-type electrode on the bottom surface of the GaN bulk crystal substrate 151 and the process of fabricating the laser diode is improved substantially. As the epitaxial layers, particularly the GaN optical waveguide layers 153 and 155 and the active layer 154 sandwiched between the layer 153 and 155 are formed epitaxially on the GaN bulk crystal substrate containing only a very small amount of defects, the quality of the crystal constituting the foregoing layers 153 - 155 is improved substantially over the conventional laser diode of FIG.1 and the laser diode 150 of FIG.20 can be driven with a large power. Further, the laser diode 150 of the present embodiment has an improved lifetime over the conventional laser diode of FIG.1.

It should be noted that the GaN bulk crystal substrate 151 may be any of the hexagonal

type or cubic type. In view of the easiness of cleaving process, on the other hand, it is preferable to form the GaN bulk crystal substrate 151 according to the process of the eleventh embodiment by using a 5 K flux.

Based on the structure of FIG.20, it is also possible to construct a light-emitting diode. Further, it is possible to construct a vertical cavity laser diode, which produces a laser beam in a 10 direction vertical to the epitaxial layers, also by using the GaN bulk crystal substrate of the present invention.

In the case of a vertical cavity laser diode, a pair of mirror surfaces defining an optical 15 cavity are formed by the epitaxial layers on the GaN bulk crystal substrate 151, and an optical window is formed in the electrode 159. In such a case, the GaN substrate 151 may have a thickness larger than  $100\mu\text{m}$  such as  $300\mu\text{m}$  or more.

20 In the laser diode of FIG.20, it is also possible to form the mirror surfaces M1 and M2 by a dry etching process.

[THIRTEENTH EMBODIMENT]

25 FIG.21 shows the construction of an

electron device 170 constructed on a GaN bulk crystal substrate 171 according to a thirteenth embodiment of the present invention.

Referring to FIG.21, the electron device 170 is an FET, and the GaN bulk crystal 102B of any of the foregoing first through twelfth embodiments is used for the GaN substrate 171.

On the substrate 171, there is provided a high-resistance epitaxial layer 172 of AlN, and a buffer layer 173 of undoped GaN is formed epitaxially on the AlN high-resistance layer 172.

On the buffer layer 173, a lower barrier layer 174 of undoped AlGaN is formed epitaxially, and a channel layer 175 of undoped GaN is formed on the lower barrier layer 174 such that the channel layer 175 is sandwiched between the lower barrier layer 174 and an upper barrier layer 176 of undoped AlGaN formed epitaxially on the channel layer 175.

The upper barrier layer 176 is covered by a contact layer 177 of n-type GaN wherein the layers 174 - 177 are patterned to form a mesa region for device isolation. Further, the contact layer 177 is patterned to expose the upper barrier layer 176 in correspondence to the channel region, and a Schottky electrode 178 of a Ni/Au structure is provided in

contact with the exposed upper barrier layer 176 as the gate electrode. Further, ohmic electrodes 179 and 180 of a Ti/Al structure are formed on the contact layer 177 at both lateral sides of the gate electrode 5 178 as a source electrode and a drain electrode, respectively.

In operation, a two-dimensional electron gas is induced in the channel layer 175 in response to application of a gate voltage to the gate 10 electrode 178. In this state, the FET is turned on.

According to the present invention, it is thus possible to construct an active device such as an FET on a GaN substrate, by using the GaN bulk crystal for the substrate. As the GaN bulk crystal 15 produced according to the present invention has an high crystal quality characterized by a defect density of  $10^2$  -  $10^3 \text{cm}^{-3}$  or less, the problem of severe leakage current that would occur when an FET is constructed on a conventional GaN epitaxial layer 20 formed on a sapphire substrate or an SiC substrate, is successfully eliminated. Further, the construction of FIG.21 is advantageous in view of the fact that the electron density of the two-dimensional electron gas induced in the channel layer 175 is increased due 25 to enhanced piezoelectric effect and associated

increase of degree of electron confinement into the channel layer. When the channel layer contains a high concentration of defects, there occurs a lattice relaxation and the effect of carrier confinement is 5 degraded inevitably.

Further, the GaN bulk crystal of the present invention can be used also as the GaN substrate of other various electron devices including a HEMT, MESFET and an HBT. In fact, the structure of 10 FIG.21 can be modified to form a HEMT by employing an n-type AlGaN layer for the upper barrier layer 176.

Further, the present invention is by no means limited to the embodiments described heretofore, but various variations and modifications may be made 15 without departing from the scope of the invention.